

Claims:

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A2
1. An apparatus for processing substrates, comprising:
- a) a transfer chamber;
 - b) one or more load lock chambers connected to the transfer chamber;
 - c) one or more process chambers connected to the transfer chamber;
 - d) a modular plumbing tray disposed adjacent the transfer chamber and having facility connections for one or more of the process chambers and the load lock chambers; and
 - e) a chamber tray disposed adjacent the one or more of the process chambers, load lock chambers and transfer chamber, the chamber tray having facility connections connected to one or more facility connections in the plumbing tray.
2. A method of processing a substrate, comprising:
- a) introducing a substrate into a load lock chamber from atmospheric pressure;
 - b) degassing and/or pre-heating the substrate in the load lock chamber;
 - c) introducing the substrate into a transfer chamber; and
 - d) processing the substrate in one or more process chambers.
3. The method of claim 2 further comprising:
- e) introducing the substrate into the load lock chamber;
 - f) cooling the substrate in the load lock chamber; and then
 - g) venting the load lock chamber to atmospheric pressure.
4. An apparatus for distributing facility to devices on a processing system, comprising:
- a) an enclosure having at least one facility interface and one or more chamber interfaces; and

5 b) one or more of a process gas manifold, vacuum manifold, water
6 manifold and a helium manifold disposed in the enclosure connected between the at
7 least one facility interface and the one or more chamber interfaces.

1 5. An apparatus for distributing facility, comprising:

2 a) a support frame having one or more of an electronics box, a gas panel, a
3 vacuum line and a controller device disposed thereon.

1- 6. A method of processing substrates, comprising:

2 a) positioning a pair of substrates on two blades on separate robots in a
3 processing system;

4 b) moving the substrates in parallel to a pair of first process chambers; and
5 then

6 c) moving the substrates in parallel to a pair of second process chambers.

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